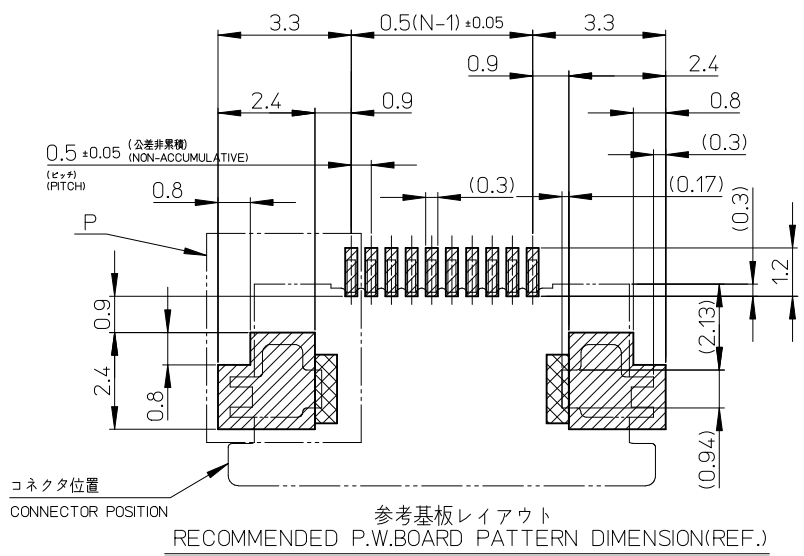


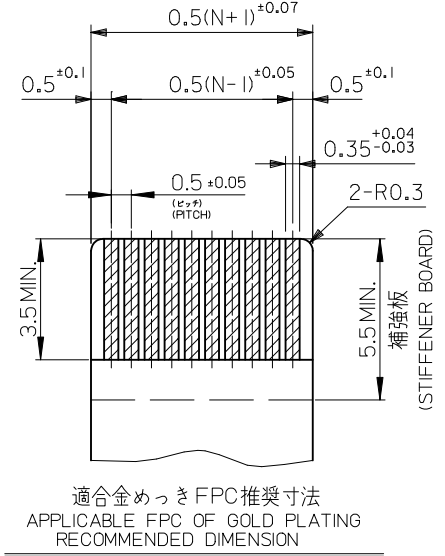
30.5	29.3	25.65	24.5	54104-5031	50
28.5	27.3	23.65	22.5	54104-4631	46
28.0	26.8	23.15	22.0	54104-4531	45
27.5	26.3	22.65	21.5	54104-4431	44
27.0	25.8	22.15	21.0	54104-4331	43
25.5	24.3	20.65	19.5	54104-4031	40
24.5	23.3	19.65	18.5	54104-3831	38
23.5	22.3	18.65	17.5	54104-3631	36
23.0	21.8	18.15	17.0	54104-3531	35
22.5	21.3	17.65	16.5	54104-3431	34
22.0	20.8	17.15	16.0	54104-3331	33
21.5	20.3	16.65	15.5	54104-3231	32
20.5	19.3	15.65	14.5	54104-3031	30
D	C	B	A	EMBOSSED PACKAGE ORDER NO.オーダー番号	CKT.

CONNECTOR SERIES NO. : 54104-**-29

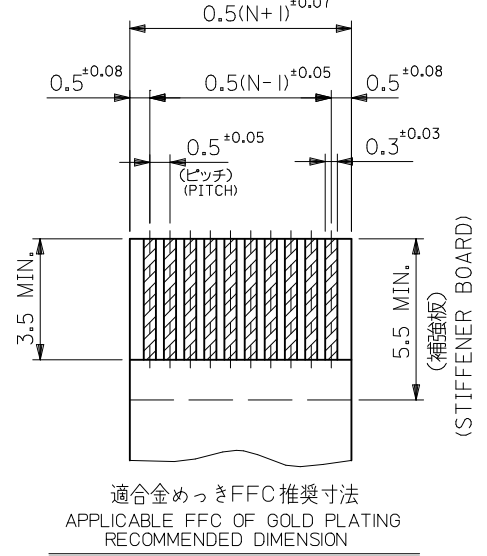
REVISED EC NO. : J2011-0041 DRW:NHI IJIMA 2010/07/07 CHK:DHI IJIMA 2010/07/07 APPR:KMORI KAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MNABEI	DATE '04/07/09	TITLE 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING					
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/07/09	MOLEX INCORPORATED					
	30 OVER	±0.3	APPROVED BY NUKITA	DATE '04/07/09	DOCUMENT NO. SD-54104-077					
REV	DESCRIPTION	ANGULAR ±3 °	MATERIAL NO. SEE SHEET 2 OF 2		SHEET NO. 1 OF 2					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



参考基板レイアウト
RECOMMENDED P.W.BOARD PATTERN DIMENSION(REF.)



適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION

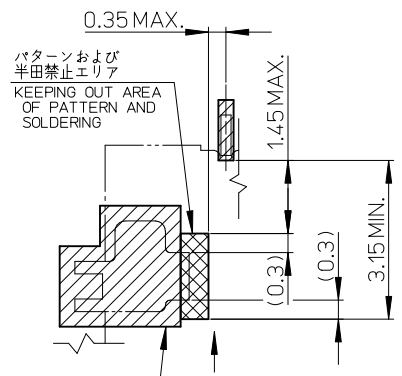


適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD PLATING
RECOMMENDED DIMENSION

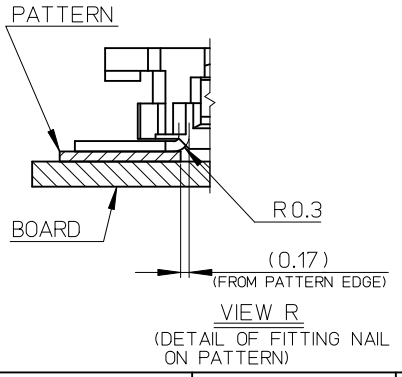
(マウント面)
(MOUNTING SIDE)

(仕上がり厚さ : 0.3±0.03)
(THICKNESS : 0.3±0.03)

(仕上がり厚さ : 0.3±0.03)
(THICKNESS : 0.3±0.03)



DETAIL P



VIEW R
(DETAIL OF FITTING NAIL ON PATTERN)

注記 NOTES

- 1.使用材料 MATERIAL
ハウジング : 46ナイロン、ガラス充填、UL94V-0、白
HOUSING:PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル : リン青銅(≒0.2) 金メッキ コンタクト部 0.1 MICROMETER MINIMUM
テール部 0.05 MICROMETER MINIMUM
ニッケル下地 1.0 MICROMETER MINIMUM
TERMINAL PHOS-BRONZE GOLD-PLATING
CONTACT PORTION : 0.1 MICROMETER MINIMUM
TAIL PORTION : 0.05 MICROMETER MINIMUM
NICKEL PLATING : 1.0 MICROMETER MINIMUM
金具 : リン青銅(≒0.2) 錫メッキ 1.0~3.0 MICROMETER MINIMUM
ニッケル下地 1.0~3.0 MICROMETER MINIMUM
FITTING NAIL : PHOS-BRONZE TIN-PLATING 1.0~3.0 MICROMETER MINIMUM
OVER NICKEL 1.0~3.0 MICROMETER MINIMUM
- 2.エンボスステップ梱包時はアクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54104-***29 SHOULD BE LOCKED.
ソルダータール半田付け面のズレ量、および金具半田付け面のズレ量は
基準面 に対して上方向 0.1MAXIMUM、下方向 0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM 基準面
UPPER DIRECTION : 0.1MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.

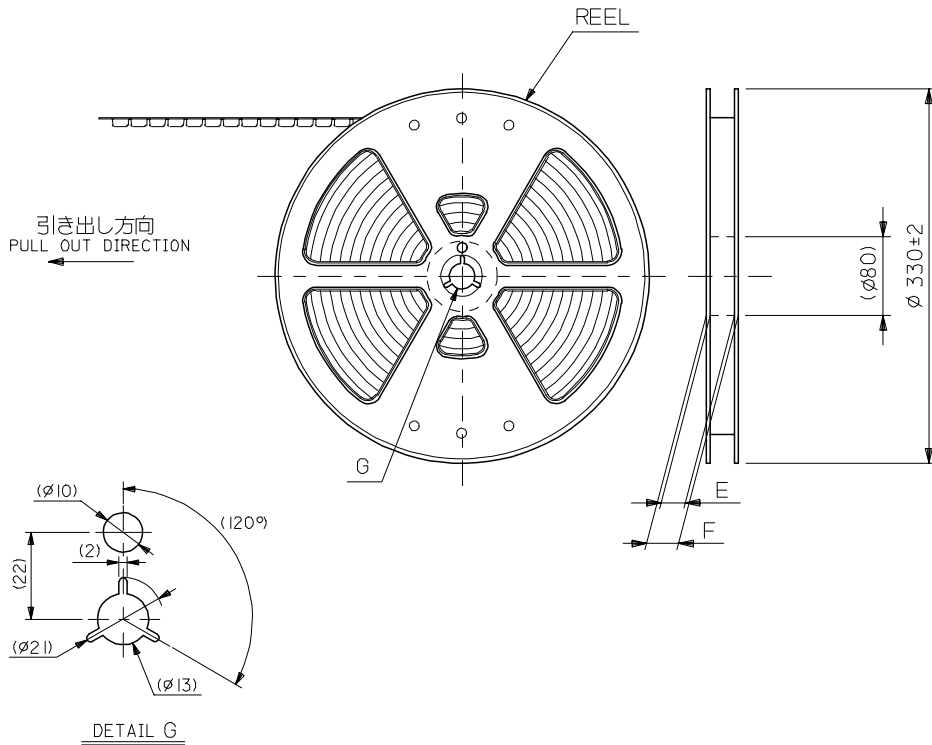
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ パターンはく離止め金具。
FITTING NAIL FOR PREVENTION OF PEELING OF P.W.BOARD PATTERN.
- 6.ELV & RoHS適合品
ELV AND RoHS COMPLIANT

FPC/FFCについて：
打ち抜き方向は導体側から補強板側を推奨いたします。
導体部は軟銅箔 35MICROMETER または 50MICROMETERを推奨いたします。
RECOMMENDED PUNCHER DIRECTION FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC THICKNESS OF SOFT COPPER FOIL : 35MICROMETERS OR 50MICROMETERS

FPCについて：
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

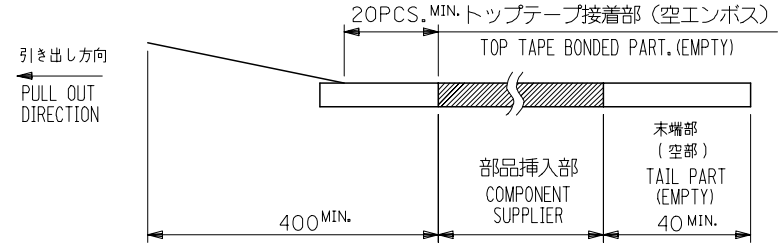
REVISED EC NO: J2011-0041 DRW:NHI IJIMA 2010/07/07 CHKD:H IJIMA 2010/07/07 APP:R:KMORI/KAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY MNABEI	DATE '04/07/09	TITLE 0.5 FPC CONN. ZIF SMT R/A UPPER CONTACT SEPARATED GOLD PLATING		
	10 OVER 30 UNDER	± ---	CHECKED BY KTOJO	DATE '04/07/09	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY NUKITA	DATE '04/07/09	SD-54104-077		
REV	ANGULAR	± --- °	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-54104-077	SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1



NOTES

1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

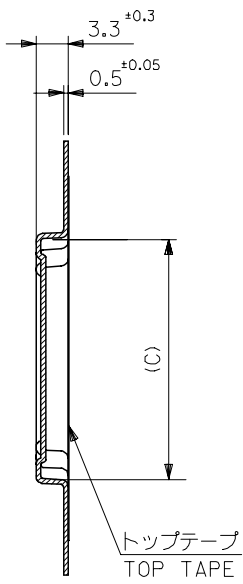


3. 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (POLYSTYLENE)
4. 本製品は 54104-**-96 のターミナル部分金メッキ品である。

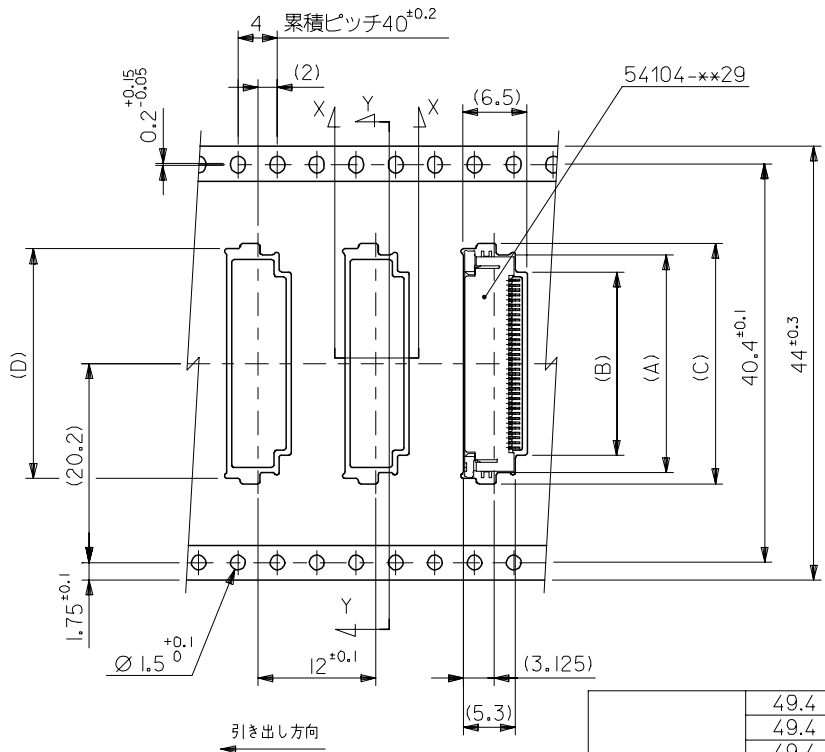
REVISED EC NO: J2007-2009 DRWN: YAMADA01 2007/01/23 CHKD: KTOYODA 2007/01/25 APPR: NUKITA 2007/01/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MNABEI	DATE '04/07/09	TITLE EMBOSSD TAPE PACKAGE FOR 54104-**-29 -LEAD FREE-	
	10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/07/09	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY NUKITA	DATE '04/07/09		
	ANGULAR	± 3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54104-078	SHEET NO. 1 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1

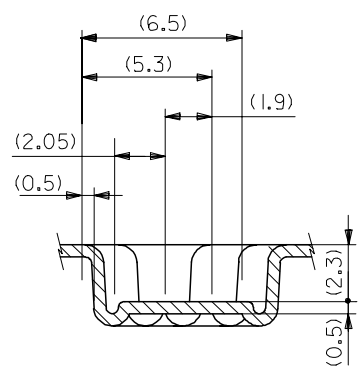
F
E
D
C
B
A



SECT:Y-Y



引き出し方向



44	49.4	45.4	30.8	31.9	26.1	29.6	54104-5031	50
	49.4	45.4	28.8	29.9	24.1	27.6	54104-4631	46
	49.4	45.4	28.3	29.4	23.6	27.1	54104-4531	45
	49.4	45.4	27.8	28.9	23.1	26.6	54104-4431	44
	49.4	45.4	27.3	28.4	22.6	26.1	54104-4331	43
	49.4	45.4	25.8	26.9	21.1	24.6	54104-4031	40
	49.4	45.4	24.8	25.9	20.1	23.6	54104-3831	38
	49.4	45.4	23.8	24.9	19.1	22.6	54104-3631	36
	49.4	45.4	23.3	24.4	18.6	22.1	54104-3531	35
	49.4	45.4	22.8	23.9	18.1	21.6	54104-3431	34
	49.4	45.4	22.3	23.4	17.6	21.1	54104-3331	33
	49.4	45.4	21.8	22.9	17.1	20.6	54104-3231	32
49.4	45.4	20.8	21.9	16.1	19.6	54104-3031	30	
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO.	CKT.

REVISED EC NO: J2007-2009 DRWN: YAMADA01 2007/01/23 CHKD: KTOYODA 2007/01/25 APPR: NUKITA 2007/01/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MNABEI	DATE '04/07/09	TITLE EMBOSSED TAPE PACKAGE FOR 54104-**-29 -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/07/09				
	30 OVER	±0.3	APPROVED BY NUKITA	DATE '04/07/09	MOLEX INCORPORATED MATERIAL NO. SEE CHART DOCUMENT NO. SD-54104-078 SHEET NO. 2 OF 2			
ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						